

die attach material in accordance with an embodiment of the present invention; [and]

[0015] FIG. 7 is an enlarged top plan view of a second pattern of die attach material in accordance with an embodiment of the present invention; and[.]

[0015.1] FIG. 8 is an enlarged cross-sectional view of a thin small outline package in accordance with an embodiment of the present invention.

Page 9, after paragraph [0032], add new paragraph [0032.1], as follows.

[0032.1] FIG. 8 is an enlarged cross-sectional view of a thin small outline package 50 in accordance with an embodiment of the present invention is shown. The TSOP 50 includes the integrated circuit die 34 attached to the base carrier 32, which in this case is a die paddle, with the extended adhesive material layer 36. The integrated circuit die 34 is electrically connected to the pins 18 of a leadframe with wires 20 in a known manner, such as by wirebonding the wires 20 to pads on the die 34 and to the leadframe pins 18. The die 34, base carrier 32, and wires 20 are encapsulated with an encapsulant, such as with the molded plastic 22.

In the Claims:

Please cancel claims 5 and 12, amend claims 3, 6 and 10, and add new claim 19, as follows.

3. (Amended) The semiconductor device of claim 2, further comprising a leadframe electrically connected to [which bonding pads of] the integrated circuit [device] die [are electrically connected].

6. (Amended) A semiconductor device, comprising:  
a base carrier having a top side and a bottom side, the top side having a central area for receiving an integrated circuit die and a peripheral area;  
an extended adhesive material layer disposed on the top side of

the base carrier, wherein the adhesive material layer is dispensed on the top side of the base carrier in an "X" shaped pattern, the "X" shaped pattern including two bisecting lines, wherein the two bisecting lines extend beyond the central area and into the peripheral area of the base carrier top surface; and

an integrated circuit die attached to the base carrier with the adhesive material layer at the central area.

10. (Amended) The semiconductor device of claim 9, further comprising a leadframe electrically connected to [which bonding pads of] the integrated circuit [device] die [are electrically connected].

--19. (New) An improved method of attaching an integrated circuit die to a base carrier, wherein a top side of the base carrier has a central area for receiving the die and a peripheral area surrounding the central area, the improvement comprising:

an extended adhesive material layer, disposed on the top side of the base carrier and covering the central area and a large portion of the peripheral area, for attaching the die to the base carrier.